

Abstract

Disclosed is an image sensor package and a method for manufacturing the same. The image sensor package comprises an image sensor die, a substrate, a support wall having screw threads on the outer peripheral surface thereof and a mount into which a barrel including a plurality of lenses and an infrared blocking glass is mounted. The screw threads formed on the outer peripheral surface of the support wall are engaged with those formed on the inner peripheral surface of the mount. At least one passive element is provided on the substrate at the outer peripheral side of the support wall, thereby increasing the packaging density of the image sensor package.